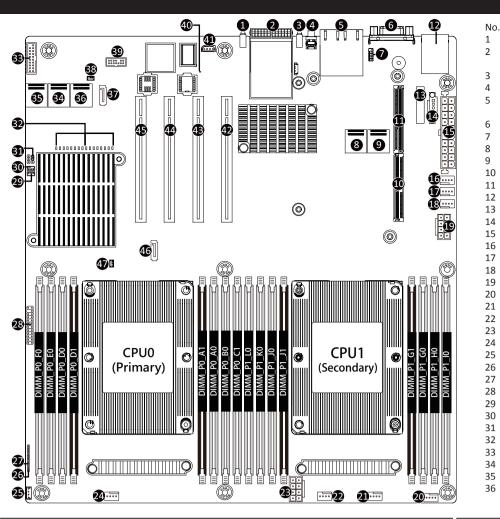
MD61-SC2 Quick Reference Guide



No.	Code	Description
1	LED LAN1	SFP+ LAN port#1 Active LED
2	SFP+ 1 2	SFP+ LAN port #1 (Left)
		SFP+ LAN port #2 (Right)
3	LED LAN2	SFP+ LAN#2 link/Active LED
4	SW ID	ID button with LED
5	LAN1 2	GbE LAN port #1 (Left)
	_	GbE LAN port #2 (Right)
6	VGA	VGA port
7	COM1	Serial port cable connector
8	U2_0	Slimline connector #1 (PCIe x4 signal)
9	U2_1	Slimline connector #2(PCIe x4 signal)
10	MEZZ_2	PCIe x 8 slot (Proprietary/for mezzanine card)
11	MEZZ_1	PCIe x 8 slot (Proprietary/for mezzanine card)
12	USB3_MLAN	Sever management LAN port (top)/USB 3.0 ports (buttor
13	BAT	Battery socket
14	PMBUS	PMBus connector
15	ATX1	2x12 pin main power connector
16	SYS_FAN5	System fan connector#5
17	CPU1_FAN1	CPU fan connector (for secondary CPU)
18	CPU0_FAN1	CPU fan connector (for primary CPU)
19	P12V_AUX2	2x4 pin 12V power connector (for secondary CPU)
20	SYS_FAN4	System fan connector#4
21	SYS_FAN3	System fan connector#3
22	SYS_FAN2	System fan connector#2
23	P12V_AUX1	2x4 pin 12V power connector (for primary CPU)
24	SYS_FAN1	System fan connector#1
25	SW_RAID	VROC key
26	LAN4_AC1	LAN#4 Active LED
27	LAN3_AC1	LAN#3 Active LED
28	FP_1	Front panel header
29	J2	Function jumper switch #2
30	J1	Function jumper switch #1
31	CLR_CMOS	Clear CMOS jumper

Error LED for DIMM slots

Slimline connector #1 (SATA 6Gb/s signal/for SATA#0~#3) Slimline connector #2 (SATA 6Gb/s signal/for SATA#4~#7) Slimline connector #3 (SATA 6Gb/s signal/for sSATA#0~#3)

USB 3.0 header

No.	Code	Description
37	SSATA5	SATA 6Gb/s connector #5
38	SATA_DOM1	SATA DOM support power connector for SSATA port #5
39	TPM	TPM connector
40	LED_BMC	BMC firmware readiness LED
41	IPMB	IPMB connector
42	PCIE_4	PCIe x16 slot #4 (Gen3 x16)
43	PCIE_3	PCIe x16 slot #3 (Gen3 x16)
44	PCIE_2	PCIe x16 slot #2 (Gen3 x16)
45	PCIE_1	PCIe x16 slot #1 (Gen3 x16)
46	SSATA4	SATA 6Gb/s connector #4
47	SATA_DOM0	SATA DOM support power connector for SSATA port #4

	Front Pane	l Hea	der #1	ВМС	Firm	ware Readiness LED
No. 1 2 3 5 7 9 11 13 15 17 324 21 23	Pin Define Power LED+ No Pin Power LED- HDD LED+ HDD LED- Power Button GND Reset Button GND ID Button GND NMI Switch	No. 2 4 6 8 10 12 14 16 18 20 22 24	Pin Define 5V Standby ID LED+ ID LED- System Status LED+ System Status LED- LAN1 Active LED+ LAN1 Link LED- SMBus Data SMBus Clock Case Open LAN2 Active LED+ LAN2 Link LED-	BMC F	irmware State On Blink Off	Readiness LED (LED_BMC1): Description BMC firmware is initial BMC firmware is ready AC loss

ricctor	TOT SOATA POIL #4
	BMC Firmware Readiness LED
	BMC Firmware Readiness LED (LED_BMC1):
LED+ LED- :D+	State Description On BMC firmware is initial Blink BMC firmware is ready Off AC loss
:D+ -	

				ATX Power		
13 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	No. 1 2 3 4 5 6 7 8 9 10 11 12	Pin Define 3.3V 3.3V GND +5V GND +5V GND Power Good 5VSB +12V +12V 3.3V	No. 13 14 15 16 17 18 19 20 21 22 23 24	Pin Define 3.3V -12V GND PS_ON GND GND GND -5V +5V +5V GND	4 8 () () () () () () () () () ()	5 1 Pin Define GND GND GND H12V +12V +12V +12V

Pin Define

No Connect

5V

GND

No.

SATA Connector/SATA DOM

Pin Define

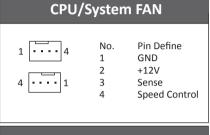
TXN

GND

RXP

GND

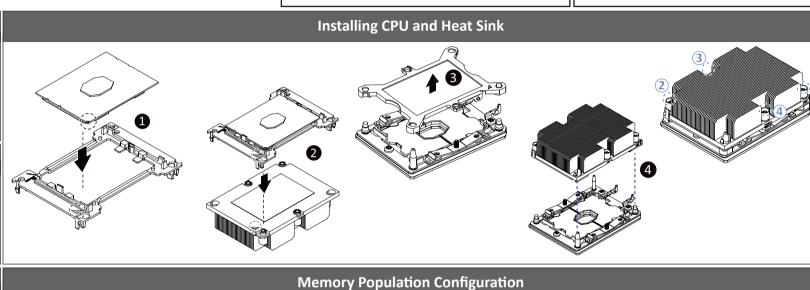
GND

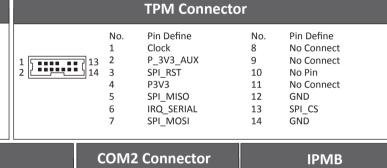


F_USB3

SL_CN1 SL_CN2 SL_CN3

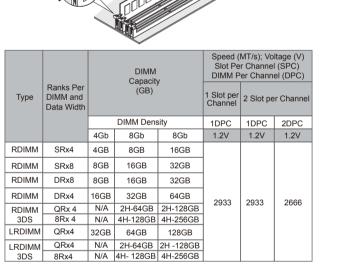
	Р	MBUS	
5 ••• •• 1	No. 1 2 3 4 5	Pin Define PMBus Clock PMBus Data PMBus Alert GND 3.3V Sense	

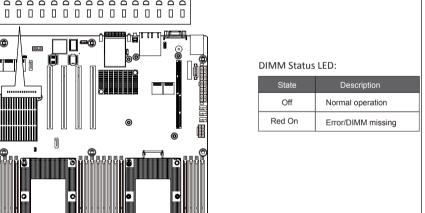


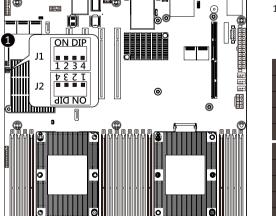


										_
		USB 3.0 H	eader		COM	12 Cc	onnector		IPMB	
20 1	No. 1 2 3 4 5 6 7 8 9 10	Pin Define Power IntA_P1_SSRX- IntA_P1_SSRX+ GND IntA_P1_SSTX- IntA_P1_SSTX+ GND IntA_P1_D- IntA_P1_D+ NC	No. 11 12 13 14 15 16 17 18 19	Pin Define IntA_P2_D+ IntA_P2_D- GND IntA_P2_SSTX+ IntA_P2_SSTX- GND IntA_P2_SSRX+ IntA_P2_SSRX- Power No Pin	10 9	No. 1 2 3 4 5 6 7 8 9 10	Pin Define NDCD- NSIN NSOUT NDTR- GND NDSR- NRTS- NCTS- NRI- No Pin	No. 1 2 3 4	Pin Define Clock GND Data VCC	

Jumper Settings







No.	Desription
1	Clear CMOS Jumper
	1-2 Close: Normal operation (Default setting
	2-3 Close: Clear CMOS data.

J1		ON	OFF				
1	HOST_SMBUS_SEL	BIOS d	efined				
2	PMBUS_SEL	BIOS defined					
3	S3_MASK	BIOS defined					
4	DB_PLD	CPLD debug mode	Normal [Default]				
J2		ON	OFF				
1	ME_UPDATE	Force ME update	Normal [Default]				
2	BIOS_PWD	Clear supervisor password	Normal [Default]				
3	BIOS_RCVR	BIOS recovery mode	Normal [Default]				
4	ME_RCVR	ME recovery mode	Normal [Default]				

2933MHz for 2nd Generation Intel® Xeon® Scalable Processors only
Intel® Optane™ DC Persistent Memory for 2nd Generation Intel® Xeon
Scalable Processors only

Intel Optane DCPMM DIMM Population Rule

Symmetric Population with the Socket													
	iMC0 iMC1												
	Channel2 Channel1				Char	nnel0	Channel2		Channel1		Channel0		
Modes	Slot1	Slot0	Slot1	Slot0	Slot1	Slot0	Slot1	Slot0	Slot1	Slot0	Slot1	Slot0	
AD		DRAM1		DRAM1	DCPMM	DRAM1		DRAM1		DRAM1	DCPMM	DRAM1	2-1-1
MM		DRAM2		DRAM2	DCPMM	DRAM2		DRAM2		DRAM2	DCPMM	DRAM2	2-1-1
AD+MM		DRAM3		DRAM3	DCPMM	DRAM3		DRAM3		DRAM3	DCPMM	DRAM3	2-1-1

Asymmetric Population with the Socket													
	iMC0 iMC1												
	Channel2 Channel1			nnel1	Chai	nnel0	Channel2		Channel1		Channel0		
Modes	Slot1	Slot0	Slot1	Slot0	Slot1	Slot0	Slot1	Slot0	Slot1	Slot0	Slot1	Slot0	
AD		DRAM1		DRAM1		DRAM1		DRAM1		DRAM1	DCPMM	DRAM1	2/1-1-1
AD*		DRAM1		DRAM1		DRAM1		DRAM1		DRAM1	DCPMM	DRAM1	2/1-1-1

- * 2nd socket has no DCPMM DIMM
- AD=All Modes; MM= Memory Mode. • For MM, general NM/FM ratio is between 1:4 and 1:16. Excess capacity for FM can be used for AD (NM= Near Memory; FM= Far Memory)

• For each individual population, sockets are normally symmetric with exceptions for 1DCPMM per socket and 1 DCPMM per node case.

	DDR4 Type				Capacity	
DRAM1	RDIMM	3DS RDIMM	LRDIMM	3DS LRDIMM	See Validation Matrix	
DRAM2	RDIMM				(DDR4 DIMMs Vaildated	
DRAM3	RDIMM	3DS RDIMM	LRDIMM		with DCPMM*)	

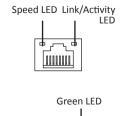
DRAM3	RDIMM	3DS RDIMM	LRDIMM		
		Capac	city		
DCDMM	Any Canacity	(uniformly for all	channols for a give	on configuration	

- Any Capacity (uniformly for all channels for a given configuration • No DDR4 single rank x8 for either DCPMM Memory Mode or APP-Direct Mode
- No mixing of DCPMM and NVDIMMs within the platform.
- DDR channel and DIMM slot nomenclature may vary depending on platform implementation.

Rear I/O Connector



- Server Management LAN port
- USB 3.0 ports VGA port
- GbE Ethernet LAN port #2
- GbE Ethernet LAN port #1
- SFP+ LAN port #2
- SFP+ LAN port #1
- ID button with LED SFP+ LAN#2 link/Active LED SFP+ LAN#1 link/Active LED



10/100/1000 LAN LED: Yellow On 1Gbps data rate 100Mbps data rate 10Mbps data rate



State	Description		
Yellow On	1 Gbps data rate		
Green On	10 Gbps data rate		

State	Description
Blue On	System identification is active.
Off	System identification is disabled.

• Matrix targets configs for optimized Intel Optane DCPMM to DRAM cache ratio in MM and MM + AD modes.

Regulatory Notices Connect With Us

WEEE Symbol Statement



The symbol shown below is on the product or on its packaging, which indicates that this product must not be disposed of with other waste. Instead, the device should be taken to the waste collection centers for activation of the treatment, collection, recycling and disposal procedure. The separate collection and recycling of your waste equipment at the time of disposal will help to conserve natural resources and ensure that it is recycled in a manner that protects human health and the environment. For more information about where you can drop off your waste equipment for recycling, please contact your local government office, your household waste disposal service or where you purchased the product for details of environmentally safe recycling.

- When your electrical or electronic equipment is no longer useful to you, "take it back" to your local or regional waste collection administration for recycling.
- If you need further assistance in recycling, reusing in your "end of life" product, you may contact us at the Customer Care number listed in your product's user's manual and we will be glad to help you with your effort.

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This product can expose you to chemicals including Lead, which is known to the State of California to cause cancer, and Bisphenol A (BPA), which is known to the State of California to cause birth defects or other reproductive harm. For more information go to www.P65Warnings.ca.gov.



Battery Warning:

Incorrectly installing a battery or using incompatible battery may increase the risk of ifre explosion. Replace the battery only with the same or equivalent type.

- Do not disassemble, crush, punchture batteries.
- Do not store or place your battery pack next to or in a heat source such as a fire, heatgenerating appliance, can or exhaust vent. Heating battery cells to temperatures above 65oC (149oF) can cause explosion or fire.
- Do not attempt to open or service batteries. Do not dispose of batteries in a fire or with household waste



电池警告:

电池安装不当或使用不兼容的电池会增加火灾爆炸风险。更换电池时,只可使用相同或同等类型的电池。

- 请勿拆解、挤压、刺破电池。
- 请勿将电池存放或放置在热源中或旁边,如火源、产生热的设备、罐体或排气口。电池温度升至65oC (149oF)以上 可能导致爆炸或火灾。
- 请勿尝试打开或维修电池。电池废弃时,请勿投入火中或者作为家庭废弃物进行处理。

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产品中有毒有害物质或元素的名称及含量

	有毒有害物质或元素(Hazardous Substances)					
部件名称(Parts)	铅(Pb)	汞(Hg)	镉(Cd)	六价铬 (Cr(VI))	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
PCB板 PCB	0	0	0	0	0	0
结构件及风扇 Mechanical parts and Fan	×	0	0	0	0	0
芯片及其他主动零件 Chip and other Active components	×	0	0	0	0	0
连接器 Connectors	×	0	0	0	0	0
被动电子元器件 Passive Components	×	0	0	0	0	0
线材 Cables	0	0	0	0	0	0
焊接金属 Soldering metal	0	0	0	0	0	0
助焊剂,散热膏,标签及其他耗材 Flux, Solder Paste, Label and other Consumable Materials	0	0	0	0	0	0
O ====================================						

〇:表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T11363-2006标准规定的限量要求以下。

∷表示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T11363-2006标准规定的限量要求。 f this part is above the limit requirement in SJ/T 11363-2006

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可能会也可能不会含有所有所列的部件。 This table shows where these substances may be found in the supply chain of our electronic formation products, as of the date of the sale of the enclosed products, Note that some of he component types listed above may or may not be a part of the enclosed product.

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